

S/N 10/606,539

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Examiner: James M. Mitchell

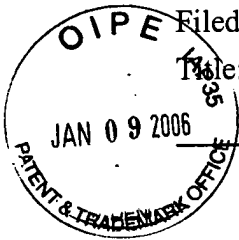
Serial No.: 10/606,539

Group Art Unit: 2813

Filed: June 26, 2003

Docket: 303.533US2

Title: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC
COOLING



AMENDMENT UNDER 37 C.F.R. § 1.312

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Notice of Allowance and Notice of Allowability mailed October 6,
2005, please amend as follows: